SEMICONDUCTOR DEVICE

ABSTRACT

A semiconductor device is disclosed that uses a sealing resin to seal a semiconductor chip and is able to prevent warpage. The semiconductor device includes a semiconductor chip; a lead frame including a chip supporter with the semiconductor chip disposed thereon, and a terminal portion that is electrically connected to the semiconductor chip; and sealing resin that seals the semiconductor chip. A first thermal expansion control member having a thermal expansion coefficient approximately equal to a thermal expansion coefficient of the lead frame is arranged on the semiconductor chip, and an upper surface of the first thermal expansion control member is nearly in the same plane as an upper surface of the sealing resin.

Fig. 4